MOSFETs Silicon N-channel MOS (U-MOSIX-H)

TK5R3A06PL

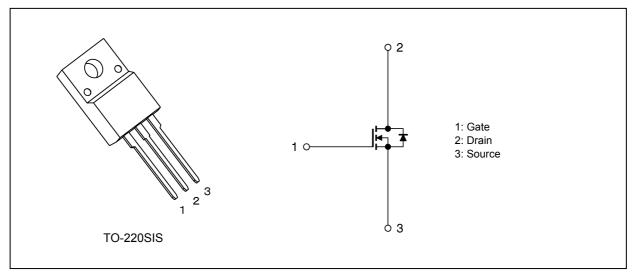
1. Applications

- High-Efficiency DC-DC Converters
- Switching Voltage Regulators
- Motor Drivers

2. Features

- (1) High-speed switching
- (2) Small gate charge: $Q_{SW} = 11 \text{ nC}$ (typ.)
- (3) Small output charge: $Q_{oss} = 32 \text{ nC}$ (typ.)
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 4.1 \text{ m}\Omega \text{ (typ.)} (V_{GS} = 10 \text{ V})$
- (5) Low leakage current: $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 60 \ V)$
- (6) Enhancement mode: V_{th} = 1.5 to 2.5 V (V_{DS} = 10 V, I_D = 0.3 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25 \ ^{\circ}C$ unless otherwise specified)

Characteristics				Rating	Unit
Drain-source voltage			V _{DSS}	60	V
Gate-source voltage			V _{GSS}	±20]
Drain current (DC)	(T _c = 25 °C)	(Note 1)	I _D	56	Α
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	Ι _D	62	A
Drain current (pulsed)	(t = 100 μs)	(Note 1)	I _{DP}	280	A
Power dissipation	(T _c = 25 °C)		PD	36	W
Single-pulse avalanche energy		(Note 3)	E _{AS}	29	mJ
Single-pulse avalanche current		(Note 3)	I _{AS}	56	Α
Channel temperature			T _{ch}	175	ů
Storage temperature			T _{stg}	-55 to 175	°C
Isolation voltage (RMS)	(t = 1.0 s)		VISO(RMS)	2000	V
Mounting torque			TOR	0.6	N · m

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristic	S	Symbol	Max	Unit
Channel-to-case thermal resistance	(T _c = 25 °C)	R _{th(ch-c)}	4.16	°C/W
Channel-to-ambient thermal resistance	(T _a = 25 °C)	R _{th(ch-a)}	62.5	

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note 2: Limited by silicon chip capability.

Note 3: V_DD = 48 V, T_ch = 25 °C (initial), L = 7.3 μ H, I_{AS} = 56 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V	_	_	±0.1	μA
Drain cut-off current	I _{DSS}	V_{DS} = 60 V, V_{GS} = 0 V	_	—	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	60	—	—	V
Drain-source breakdown voltage (Note 4)	V _{(BR)DSX}	I _D = 10 mA, V _{GS} = -20 V	45	_	_	
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 0.3 mA	1.5		2.5	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 4.5 V, I _D = 14 A		6.2	9.3	mΩ
		V _{GS} = 10 V, I _D = 28 A	_	4.1	5.3	

Note 4: If a reverse bias is applied between gate and source, this device enters V_{(BR)DSX} mode. Note that the drainsource breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz	_	2380	_	pF
Reverse transfer capacitance	C _{rss}		_	50	—	
Output capacitance	C _{oss}]	_	470	_	
Gate resistance	r _g	—	—	1.4	—	Ω
Switching time (rise time)	t _r	See Fig. 6.2.1	_	6	—	ns
Switching time (turn-on time)	t _{on}]	_	19	_	
Switching time (fall time)	t _f]	_	7	_	
Switching time (turn-off time)	t _{off}		_	35	_	

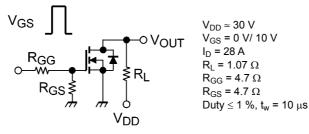


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25$ °C unless otherwise specified)

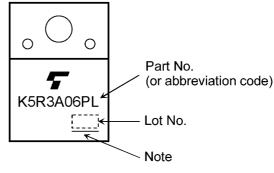
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Qg	$V_{DD} \approx 30$ V, V_{GS} = 10 V, I_D = 28 A	_	36	_	nC
gate-drain)		$V_{DD} \approx 30$ V, V_{GS} = 4.5 V, I_D = 28 A	_	18	—	
Gate-source charge 1	Q _{gs1}	$V_{DD} \approx 30$ V, V_{GS} = 10 V, I_D = 28 A	_	9.0	_	
Gate-drain charge	Q _{gd}		_	6.5	_	
Gate switch charge	Q _{SW}		_	11	—	
Output charge	Q _{oss}	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz	_	32	_	

6.4. Source-Drain Characteristics ($T_a = 25 \ ^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note 5)	I _{DRP} (t = 100 μs)	—	—	—	280	A
Diode forward voltage	V _{DSF}	I _{DR} = 56 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time	t _{rr}	I _{DR} = 14 A, V _{GS} = 0 V,	_	40	_	ns
Reverse recovery charge	Q _{rr}	-dI _{DR} /dt = 100 A/μs		38	_	nC

Note 5: Ensure that the channel temperature does not exceed 175 $^\circ \text{C}.$

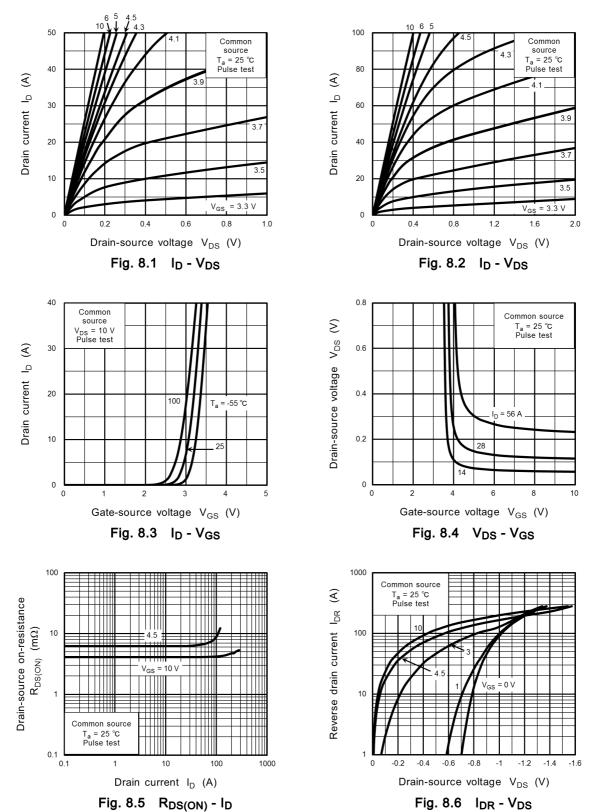
7. Marking (Note)



- Fig. 7.1 Marking
- Note: A line under a Lot No. identifies the indication of product Labels. Not underlined: [[Pb]]/INCLUDES > MCV Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]] Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the

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8. Characteristics Curves (Note)



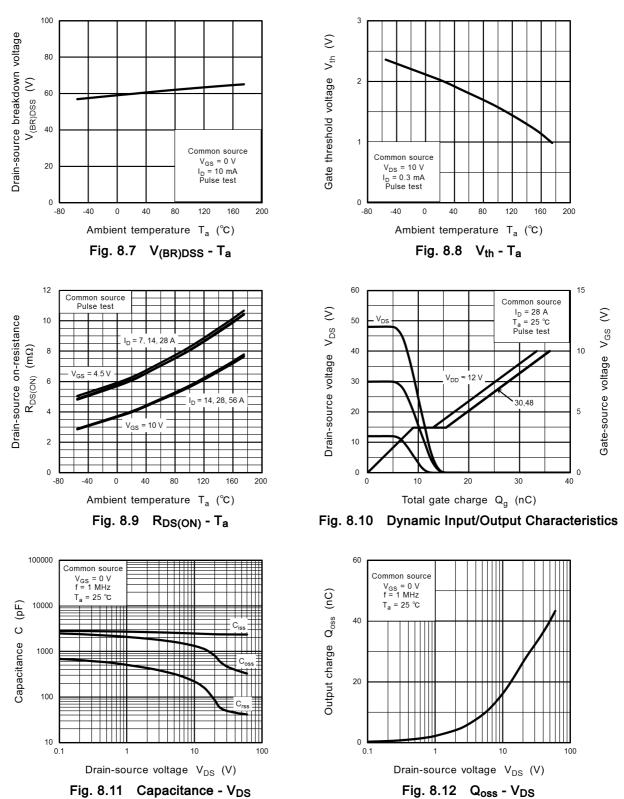
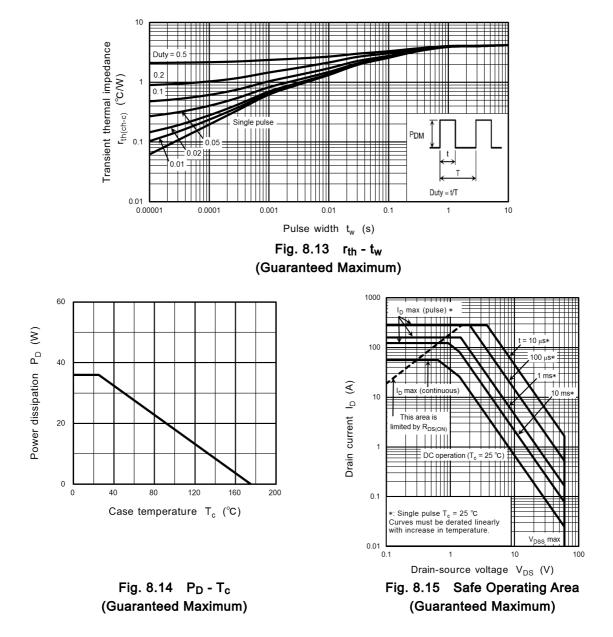


Fig. 8.11 Capacitance - V_{DS}

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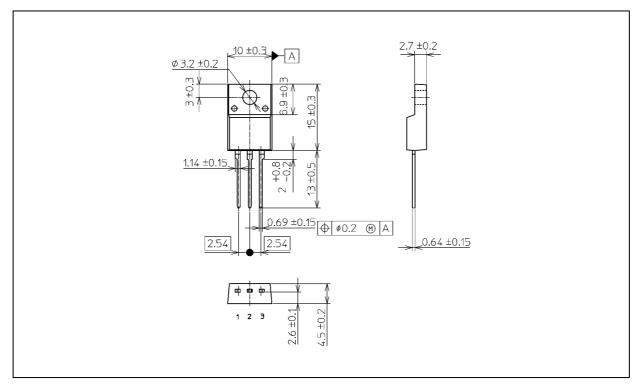


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

TK5R3A06PL

Package Dimensions

Unit: mm



Weight: 1.56 g (typ.)

Package Name(s)			
TOSHIBA: 2-10U1S			
Nickname: TO-220SIS			

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